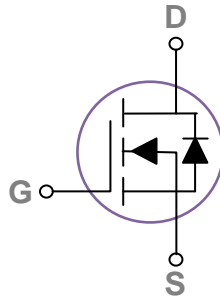
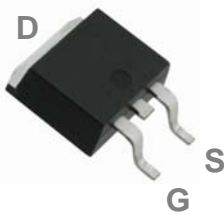


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDSON	ID
20V	25mΩ	20A

### Features

- 20V, 20A,  $R_{DS(ON)} = 25m\Omega @ V_{GS} = 4.5V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Hand-Held Instruments
- Networking

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	20	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	12	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	80	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	20.8	W
	Power Dissipation – Derate above $25^\circ C$	0.167	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	6	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1mA$	---	0.02	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=85\text{ }^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=4A$	---	21	25	m $\Omega$
		$V_{GS}=2.5V, I_D=3A$	---	28	36	
		$V_{GS}=1.8V, I_D=2A$	---	39	51	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.4	0.6	1	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2	---	$mV/^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V, I_S=3A$	---	7	---	S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=10V, V_{GS}=4.5V, I_D=4A$	---	7.7	11	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.9	1	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	2.4	5	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega$ $I_D=1A$	---	4.1	8	nS
$T_r$	Rise Time <sup>2,3</sup>		---	11.6	22	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	23.9	45	
$T_f$	Fall Time <sup>2,3</sup>		---	7.6	14	
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, F=1MHz$	---	535	775	pF
$C_{oss}$	Output Capacitance		---	60	85	
$C_{rss}$	Reverse Transfer Capacitance		---	34	50	

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	20	A
$I_{SM}$	Pulsed Source Current		---	---	40	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

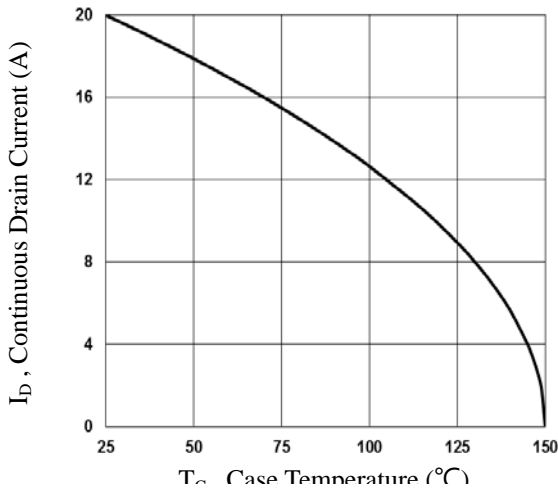


Fig.1 Continuous Drain Current vs.  $T_c$

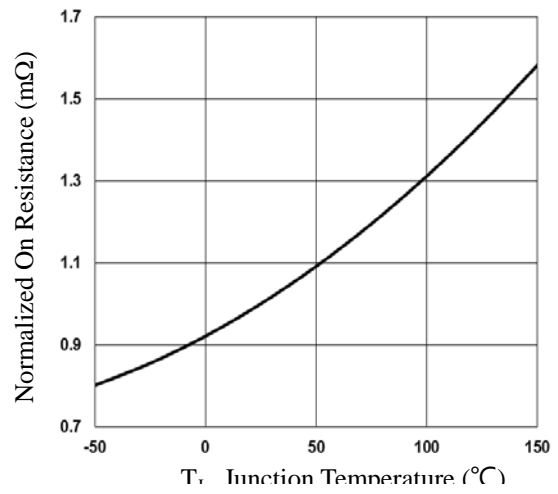


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$

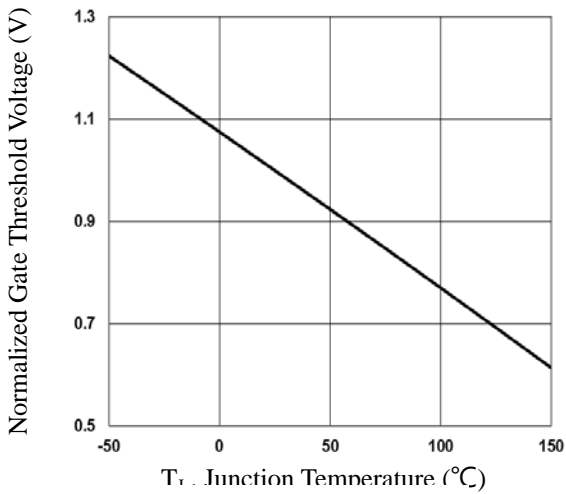


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

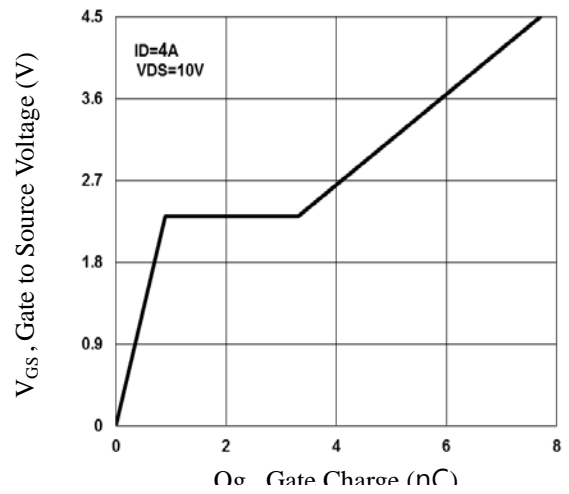


Fig.4 Gate Charge Waveform

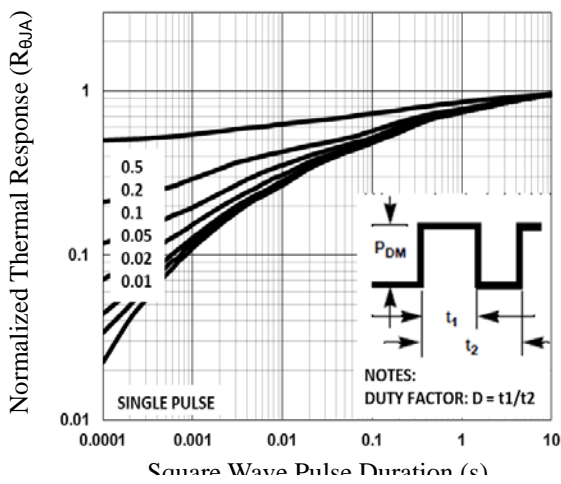


Fig.5 Normalized Transient Impedance

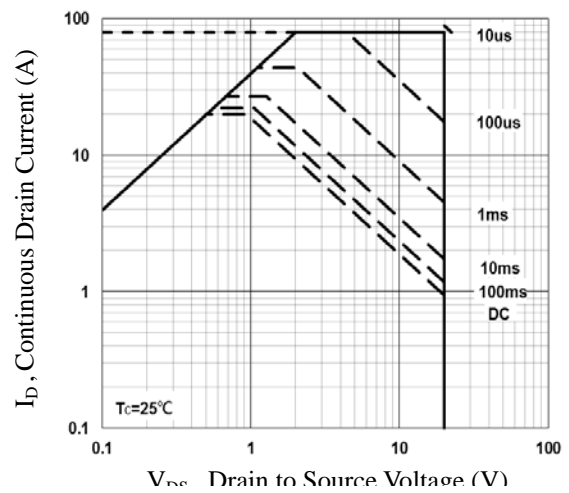


Fig.6 Maximum Safe Operation Area

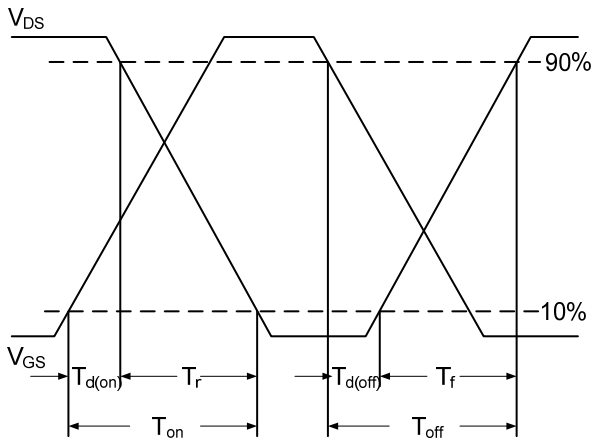


Fig.7 Switching Time Waveform

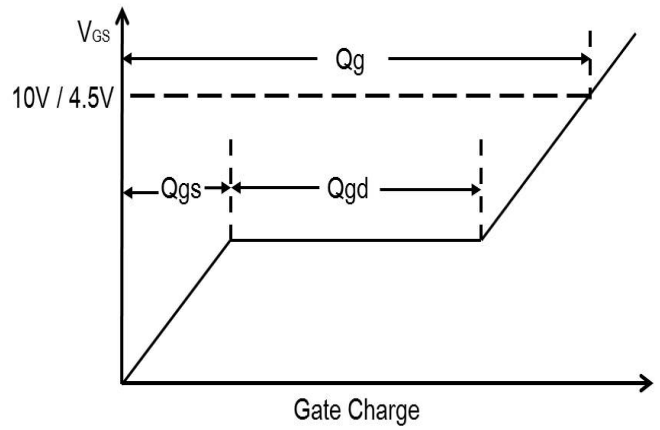
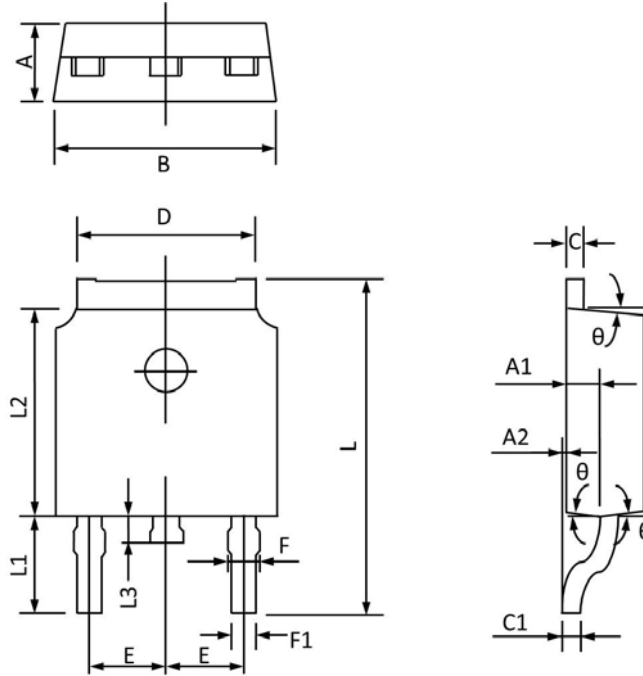


Fig.8 Gate Charge Waveform

## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
$\theta$	3°	9°	3°	9°